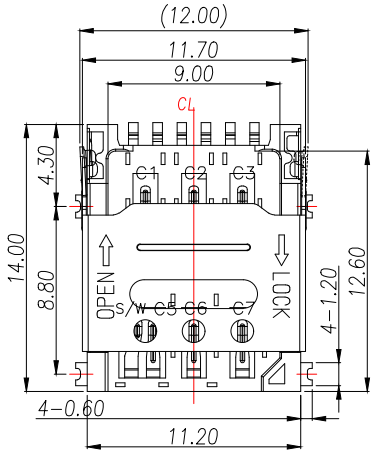
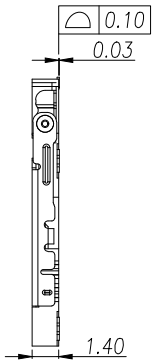
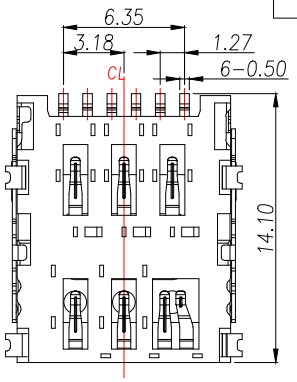
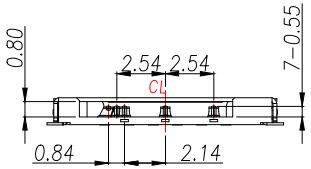
REV.	DESCRIPTION	ECN NO.	NAME	DATE

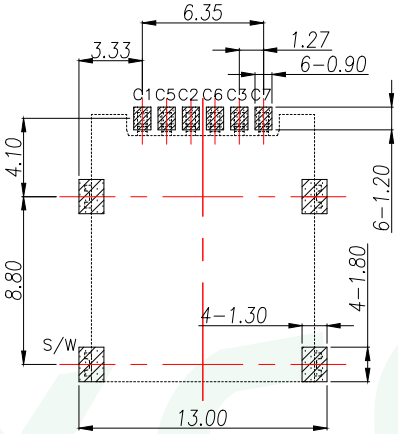








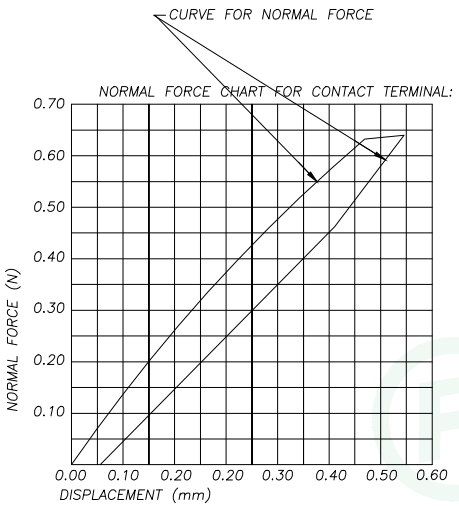
NANO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A
S/W	Switch Pin



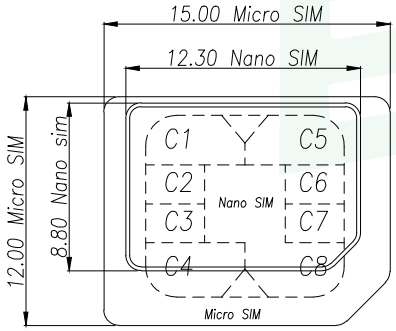
PAD AREA

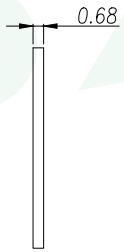
RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05

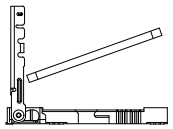


NOTES:
1. MATERIAL:
   1.1 Housing:High Temperature Thermoplastic UL94V-0; Color Black.
   1.2 Terminal:Copper Alloy,T=0.12mm.
   1.3 Shell:Stainless Steel,T=0.20mm.
2. FINISH:
   2.1 Terminal:Plated Gold on The Contact Area and Solder Tails
   2.2 Peg:Plated Gold on the Solder Tails.
3. SPECIALITY:
   3.1 Rated current:0.5A
   3.2 Rated voltage:50V
   3.3 Contact Resistance:80mΩMAX
   3.4 Insulation Resistance:100MΩMIN 100V DC
   3.5 Dielectric withstanding voltage: 100V AC.
   3.6 Solder ability:245±5°C,5±0.5s.
   3.7 Operating condition:Temperature: -30°C~+80°C
   Humidity: 80% R.H MAX

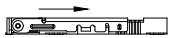




Circuit Diagram for Card Detect Switch	
WITH CARD	WITH OUT CARD
S/W	S/W
C5	C5



STEP 1 INSERT NANO SIM CARD

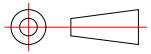


STEP 2 PUSH THE SHELL

STEP 3 FINISH

NO.	PART NAME	Q'TY	DESCRIPTION	NOTE
③	TERMINAL	6	C5210-EH,T=0.12	Au 3u" PLATING
②	BASE INSULATOR	1	LCP+GF30%	BLACK
①	SHELL	1	SUS304-H,T=0.15	AU/Ni PLATING

GENERAL TOLERANCE	
DIM.	TOL.
X	
X.X	±0.30
X.XX	±0.25
X.XXX	±0.15
GENERAL ANGLE:	±3°



DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD

BXCONN®

TITLE: 7pin 1.4h higne namo sim card conn.

DWG. NO.:	SIM301-GZ7P	DRAWN:	MAX
PART NO.:	SIM301-GZ7P	CHECKED:	ELLA

UNIT:	SCALE:	SHEET:	DWG. SIZE:	LAYER:	APPROVED:
mm	none	1of 1	A4	bxconn	WILL